

HEXFRED® Ultrafast Soft Recovery Diode, 220 A



PRODUCT SUMMARY					
V_{R}	1200 V				
V _F (typical)	2.68 V				
t _{rr} (typical)	58 ns				
$I_{F(AV)}$ per module at T_C	220 A at 38 °C				
Package	SOT-227				

FEATURES

- · Fast recovery time characteristic
- · Electrically isolated base plate
- · Large creepage distance between terminal
- · Simplified mechanical designs, rapid assembly
- · Designed and qualified for industrial level
- UL approved file E78996



DESCRIPTION / APPLICATIONS

The dual diode series configuration (VS-HFA220FA120) is used for output rectification or freewheeling/clamping operation and high voltage application.

The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built.

These modules are intended for general applications such as HV power supplies, electronic welders, motor control and inverters.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	V _R		1200	V	
Continuous forward current (1)	I _F	T _C = 68 °C	110	Α	
Single pulse forward current	I _{FSM}	T _J = 25 °C	700	A	
Marian and a second distribution of the second	В	T _C = 25 °C	500	W	
Maximum power dissipation per leg	P _D	T _C = 100 °C	400	VV	
RMS isolation voltage	V _{ISOL}	Any terminal to case, t = 1 minute	2500	V	
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	1200	-	-	
Forward voltage		I _F = 100 A	-	2.68	3.60	
	\ \ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\	I _F = 200 A	-	3.41	4.70	V
	V_{FM}	I _F = 100 A, T _J = 150 °C	-	2.62	2.89	
		I _F = 200 A, T _J = 150 °C	-	3.59	3.89	
		V _R = V _R rated	-	10	75	μΑ
Reverse leakage current	I _{RM}	T _J = 125 °C, V _R = V _R rated	-	2	-	mA
		T _J = 150 °C, V _R = V _R rated	-	6	15	IIIA

Note

⁽¹⁾ Maximum continuous forward current must be limited at 100 A to do not exceed the maximum temperature of power terminals.



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST	TEST CONDITIONS		TYP.	MAX.	UNITS
		$I_F = 1 A; dI_F/dt$: = - 200 A/μs; V _R = 30 V	-	58	-	
Reverse recovery time	t _{rr}	T _J = 25 °C		-	157	-	ns
		T _J = 125 °C	•	-	255	-]
Deals received a current		T _J = 25 °C	I _F = 50 A	-	15	=	^
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = -200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	22.5	-	A
Reverse recovery charge Q _{rr}		T _J = 25 °C	VN - 200 V	-	1150	-	nC
	Q _{rr}	T _J = 125 °C		-	2850	=	IIC
Junction capacitance	C _T	V _R = 1200 V		-	53	=	pF

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction to case, single leg conducting	Ь		-	-	0.25	
Junction to case, both legs conducting	- R _{thJC}		-	-	0.125	°C/W
Case to heatsink	R _{thCS}	Flat, greased surface	-	0.10	-	
Weight			-	30	-	g
Mounting torque		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
		Torque to heatsink	-	-	1.3 (11.5)	Nm (lbf.in)
Case style					SOT-227	•

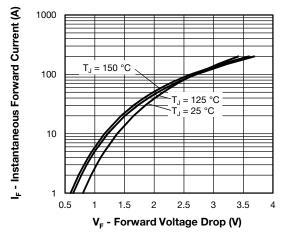


Fig. 1 - Typical Forward Voltage Drop Characteristics (Per Leg)

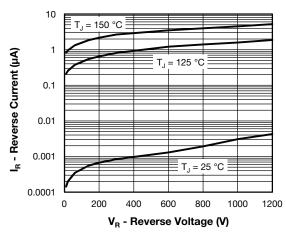


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

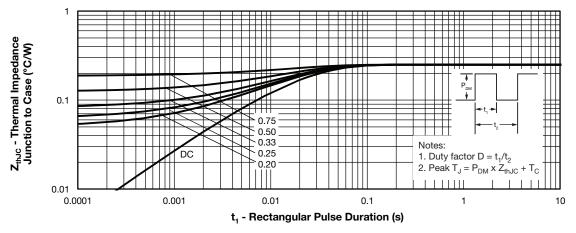


Fig. 3 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

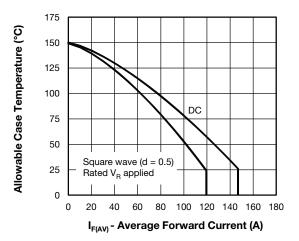


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

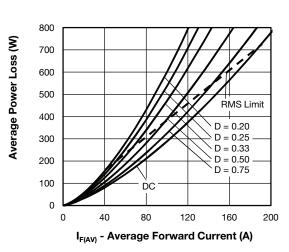


Fig. 5 - Forward Power Losses Characteristics (Per Leg)

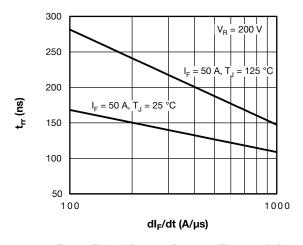


Fig. 6 - Typical Reverse Recovery Time vs. dI_{F}/dt

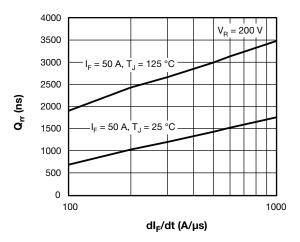
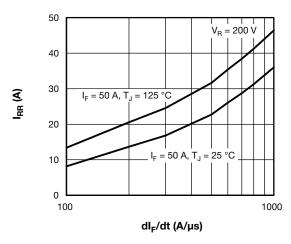


Fig. 7 - Typical Stored Charge vs. dl_F/dt

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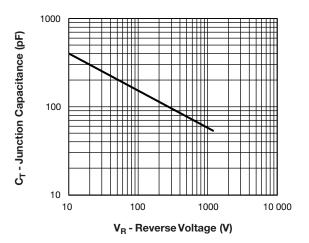


Fig. 9 - Typical Junction Capacitance vs. Reverse Voltage

Note

 $\begin{array}{l} \text{(1)} \ \ \text{Formula used:} \ T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \ \text{at} \ (I_{F(AV)}/D) \ \text{(see fig. 5)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \ \text{(1 - D)}; \ I_R \ \text{at} \ V_{R1} = Rated \ V_R \\ \end{array}$

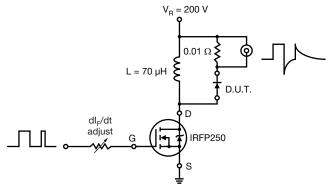
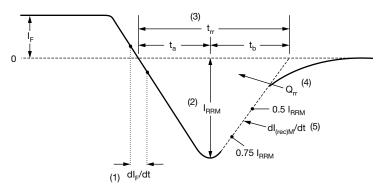


Fig. 10 - Reverse Recovery Parameter Test Circuit



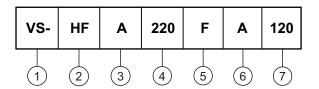
- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}
 - $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (5) dl_{(rec)M}/dt peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



- 1 Vishay Semiconductors product
- 2 HEXFRED® family
- Process designator (A = electron irradiated)
- 4 Average current (220 = 220 A)
- 5 Circuit configuration (2 separate diodes, parallel pin-out)
- 6 Package indicator (SOT-227 standard insulated base)
- Voltage rating (120 = 1200 V)

CIRCUIT CONFIGURATION					
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING			
2 separate diodes, parallel pin-out	F	Lead Assignment 4 0 3 4 1 0 3 3			

LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95423</u>					
Packaging information	www.vishay.com/doc?95425				



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